#### Assuring CubeSat Electric Power Systems

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# **CubeSat Challenge**

- Normal mission
  - Requirement driven
  - Blanket risk reduction
- CubeSat mission
  - Risk driven
  - Cost-trade analysis at every step
- Radiation is a slippery target
  - Mission based testing approach
  - Decide between test as you fly and worst case
  - The mission duration and target drives the test conditions



# **Space environments - LEO**

- For low inclination orbit (12 months)
  - 27 krad(Si) on the surface with an RDF of 2
  - 0.985 krad(Si) after 50 mils
    Al with an RDF of 2
  - 0.979 krad(Si) after 100 mils
    Al with an RDF of 2
- Single Event Environment is benign
- Test condition is to 5 krad(Si) and LET 37 MeV.cm<sup>2</sup>/mg



LET (MeV-cm<sup>2</sup>/mg)



Almunium Shielding Thickness, mil



- For trip to Mars (9 months)
  - 175 krad(Si) on the surface with an RDF of 2
  - 6.3 krad(Si) after 50 mils Al with an RDF of 2
  - 2.9 krad(Si) after 100 mils Al with an RDF of 2
- For trip to Jupiter (12 months at site)
  - >1000 krad(Si) on the surface with an RDF of 2
  - 50-200 krad(Si) after 50 mils
    AI with an RDF of 2
  - 10-50 krad(Si) after 100 mils
    Al with an RDF of 2
- Test condition is to 50 krad(Si) and LET 37 MeV.cm<sup>2</sup>/mg



Spherical Shell Aluminum Shielding Thickness (mil)

To be presented at the 5th NASA Electronic Parts and Packaging (NEP NASA GSFC, Gree



## **CubeSat Architectures**

- CubeSats defy typical space craft design
  - Small and low power mission forces single chip designs
- Reliance on one or two key components
  - Boost/buck or similar converter
  - Logic level power FETs
  - Classic DC/DCs are too big and inflexible
- No discrete systems
  - No ability to assure the system in the design
  - SEE effects on key devices are system SEE



## **Task Approaches**

- Identify known parts in service
  - Reconnoitering available CubeSat system providers
  - Contacting when available
- Identify enabling parts and technology
  - The similarity of all technologies used allows for consolidation of parts evaluation
  - Identification of uniformly vetted parts
- Test to maximize risk reduction
  - Test to typical extra-orbital deployments
  - TID to 50 krad(Si)
  - SEE to 37 MeV.cm2/mg



# **Task implementation**

#### Identify high value parts

- Current inflight service
- High risk parts
- High use parts
- Part list management
  - As held by Kathryn Beckwith
  - Other identified parts held separately
- Test data separate from user or application
  - SEE and TID performance don't require
  - Test is usual case
    - Eval cards
    - Typical bias

# Inflight power parts SEE – Boost/buck



No load current, room temp, and BNL

# Inflight Tech – SEE in Power MOSFET



- No angular effect

To be presented at the 5<sup>th</sup> NASA Electronic Parts and Packaging (NEPP) Program Electronic Technology Workshop June 23-26, 2015, NASA GSFC, Greenbelt, MD.

# **Enabling Tech – TID in MOSFETs**







- Epitaxial layer is less than 10 um
- No angular effect

To be presented at the 5<sup>th</sup> NASA Electronic Parts and Packaging (NEPP) Program Electronic Technology Workshop June 23-26, 2015, NASA GSFC, Greenbelt, MD.

## Conclusion



- COTS performance are as expected
  - TID performance ranges from 1 to 50 krad(Si)
  - SEE performance typical for commercial CMOS
  - SEGR performance better for low power MOSFET
- CubeSat power systems are boiling down to a few "go-to" options
  - Monolithic boost/buck is the favorite
  - Other buck options in study
  - Lower power MOSFETs can be analytically bounded



# Thank you.

# **QUESTIONS?**

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